

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1266	(lead or tab or tape) adj frame and pad and test same pad and (lead or wire) same bond\$4 and (die or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:44
L2	1205	1 and (bond\$4 or attach\$5 or affix\$4) same (die or chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:44
L3	617	2 and (overmould\$4 or overmold\$4 or encapsulat\$4 or underfill\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:45
L4	225	3 and test\$4 and (burn adj in or "burn-in")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:46
L5	38	4 and footprint	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:47
L6	153	4 and test same probe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:46
L7	60	6 and (tab or tape near bond\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:47
L8	11	7 and footprint	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 13:47